

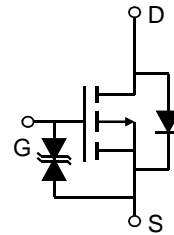
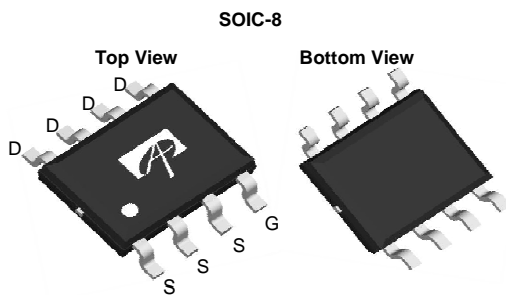
General Description

The AO4423 uses advanced trench technology to provide excellent $R_{DS(ON)}$, and ultra-low gate charge with a 25V gate rating. This device is suitable for use as a load switch or in PWM applications.

Product Summary

V_{DS} (V) = -30V
 I_D = -17A ($V_{GS} = -20V$)
 $R_{DS(ON)} < 6.2m\Omega$ ($V_{GS} = -20V$)
 $R_{DS(ON)} < 7.2m\Omega$ ($V_{GS} = -10V$)

ESD Protected
 100% UIS tested
 100% Rg tested (note *)



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 25	V
Continuous Drain Current ^{AF}	I_D	$T_A=25^\circ\text{C}$	-17
		$T_A=70^\circ\text{C}$	-14
Pulsed Drain Current ^B	I_{DM}	-182	A
Power Dissipation ^A	P_D	$T_A=25^\circ\text{C}$	3.1
		$T_A=70^\circ\text{C}$	2
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^{AF}	$R_{\theta JA}$	$t \leq 10s$	26	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A		Steady-State	50	$^\circ\text{C/W}$
Maximum Junction-to-Lead ^C	$R_{\theta JL}$	14	24	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$, $V_{GS}=0\text{V}$			-1	μA
		$T_J=55^\circ\text{C}$			-5	
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			± 1	μA
		$V_{DS}=0\text{V}$, $V_{GS}=\pm 25\text{V}$			± 10	μA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-1.5	-2.1	-2.6	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-10\text{V}$, $V_{DS}=-5\text{V}$	-182			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-20\text{V}$, $I_D=-15\text{A}$		5.1	6.2	$\text{m}\Omega$
		$T_J=125^\circ\text{C}$		7.4	9	
		$V_{GS}=-10\text{V}$, $I_D=-15\text{A}$		5.9	7.2	$\text{m}\Omega$
		$V_{GS}=-6\text{V}$, $I_D=-10\text{A}$		7.5	9.5	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=-5\text{V}$, $I_D=-15\text{A}$		48		S
V_{SD}	Diode Forward Voltage	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$		-0.71	-1	V
I_S	Maximum Body-Diode Continuous Current				-4.2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=-15\text{V}$, $f=1\text{MHz}$		2527	3033	pF
C_{oss}	Output Capacitance			583		pF
C_{riss}	Reverse Transfer Capacitance			397	556	pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$	2.1	4.3	6.4	Ω
SWITCHING PARAMETERS						
Q_g	Total Gate Charge	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $I_D=-15\text{A}$		47	57	nC
Q_{gs}	Gate Source Charge			8		nC
Q_{gd}	Gate Drain Charge			14		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=-10\text{V}$, $V_{DS}=-15\text{V}$, $R_L=1.0\Omega$, $R_{GEN}=3\Omega$		12		ns
t_r	Turn-On Rise Time			8		ns
$t_{D(off)}$	Turn-Off DelayTime			54		ns
t_f	Turn-Off Fall Time			87		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-15\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		26.1	32	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-15\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		12.3		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D: The static characteristics in Figures 1 to 6 are obtained using $<300\mu\text{s}$ pulses, duty cycle 0.5% max.

E: These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

F: The current rating is based on the $t \leq 10\text{s}$ junction to ambient thermal resistance rating.

Note *: This device is guaranteed RG 100% tested after date code 8V11 (Jan 1st 2008)

Rev10: May. 2012

THIS PRODUCT HAS BEEN DESIGNED AND QUALIFIED FOR THE CONSUMER MARKET. APPLICATIONS OR USES AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED. AOS DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS. AOS RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN, FUNCTIONS AND RELIABILITY WITHOUT NOTICE

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

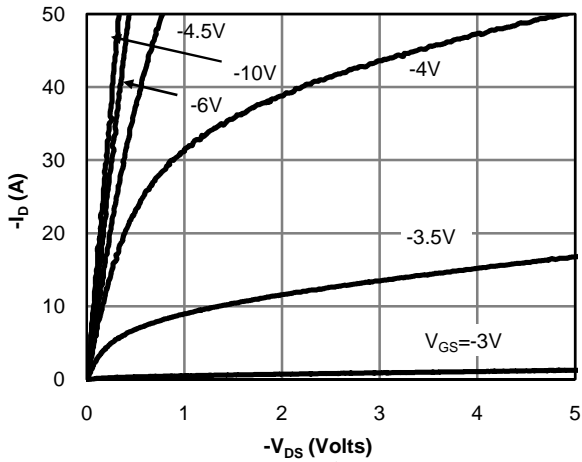


Fig 1: On-Region Characteristics

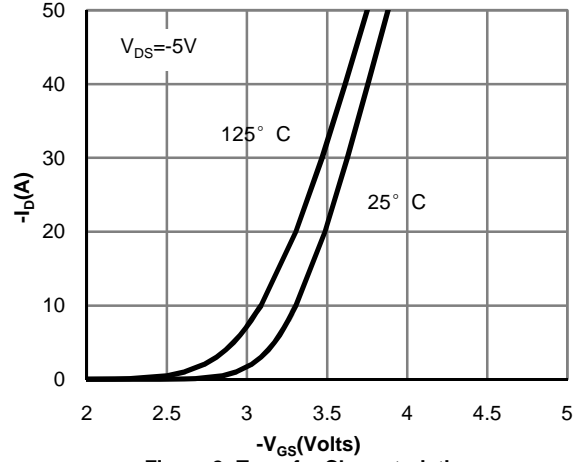


Figure 2: Transfer Characteristics

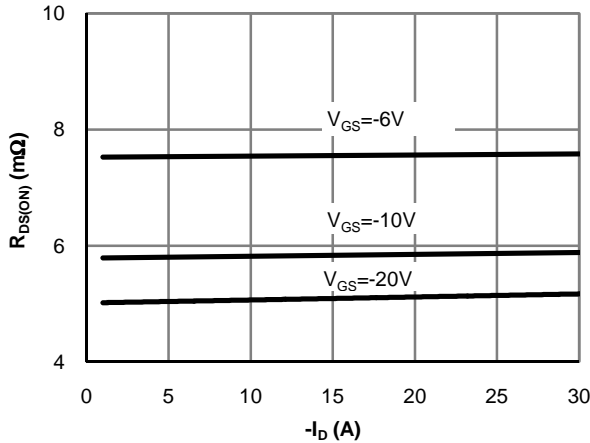


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

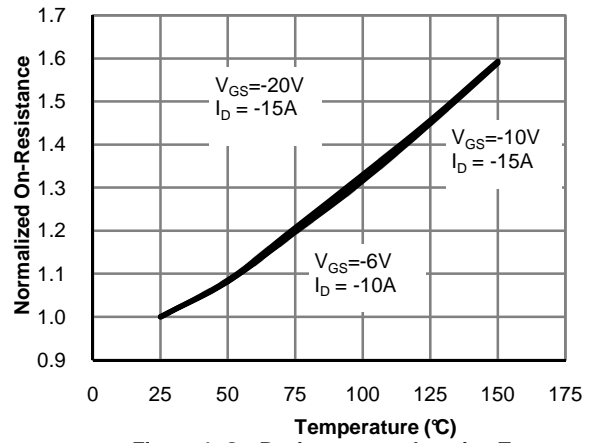


Figure 4: On-Resistance vs. Junction Temperature

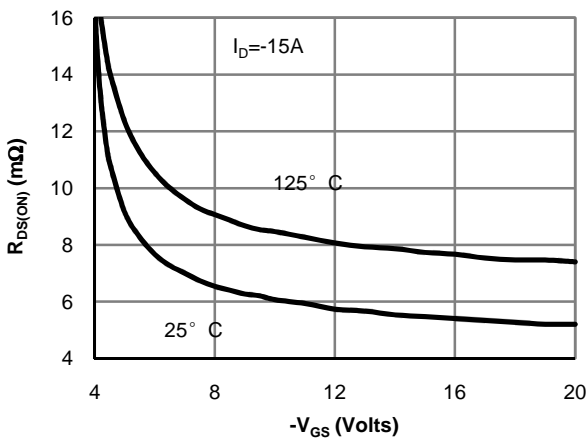


Figure 5: On-Resistance vs. Gate-Source Voltage

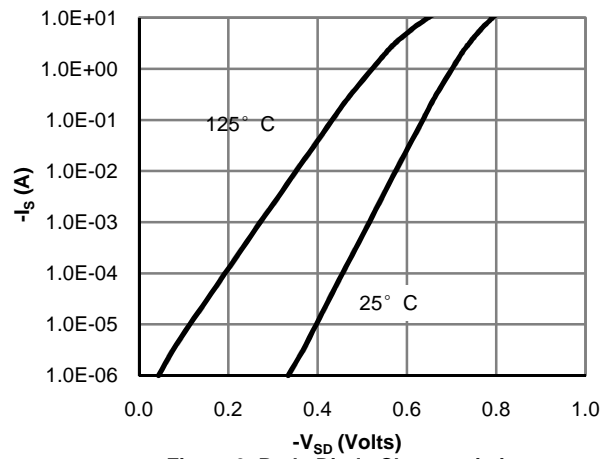


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

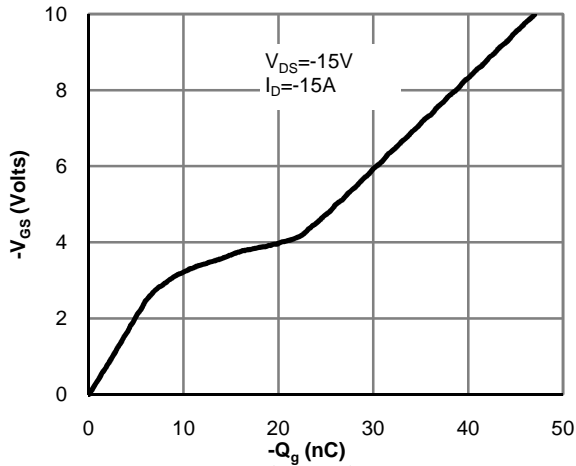


Figure 7: Gate-Charge Characteristics

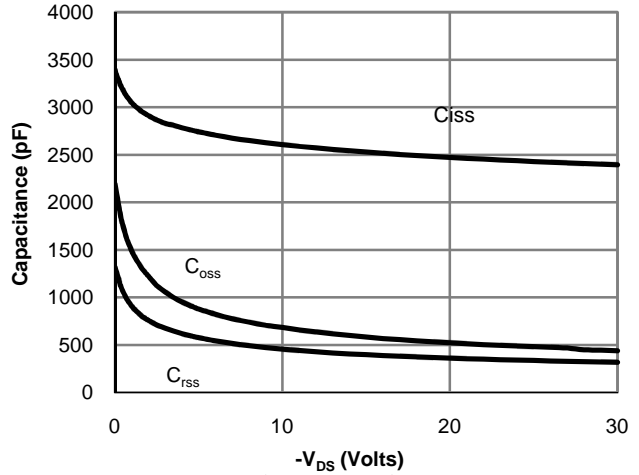


Figure 8: Capacitance Characteristics

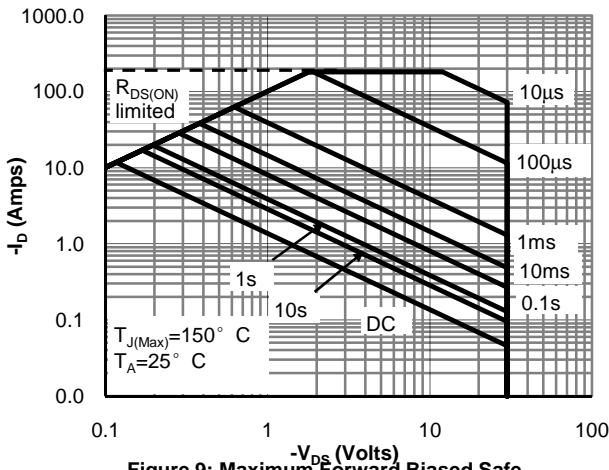


Figure 9: Maximum Forward Biased Safe

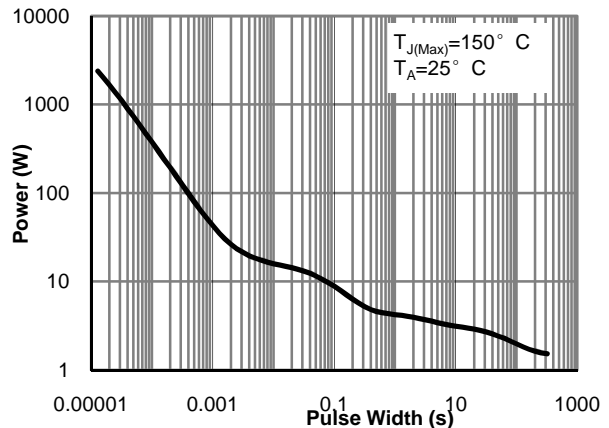


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

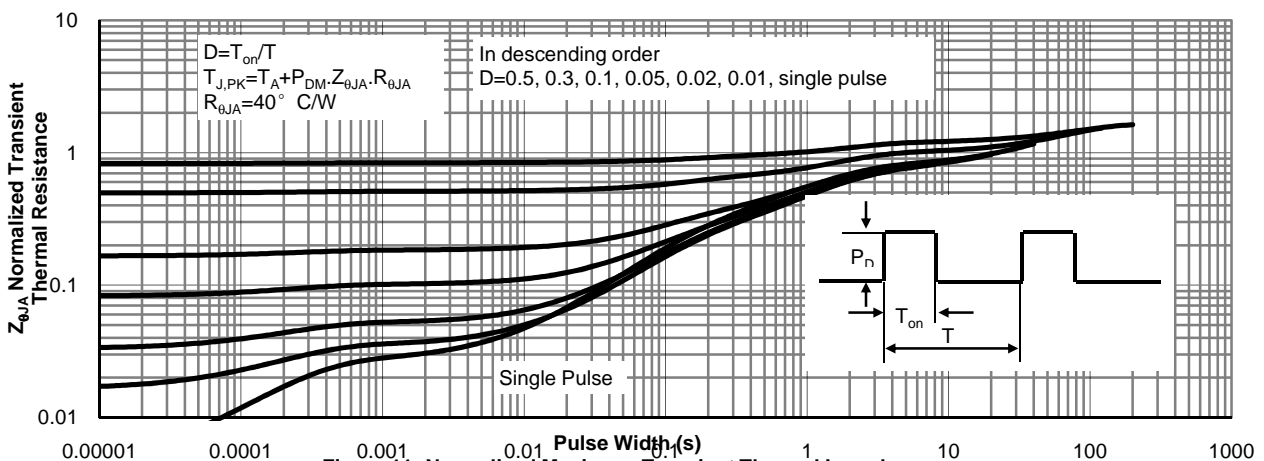


Figure 11: Normalized Maximum Transient Thermal Impedance